What is claimed is:

1. A process of packaging an organic electroluminescent panel, the electroluminescent panel comprising a transparent substrate, a plurality of anodes formed on the transparent substrate, wherein each of the anodes has a driving area and at least one connecting area laterally connected to the driving area, a patterned organic electroluminescent layer formed on the transparent substrate or on the anodes, wherein the patterned organic electroluminescent layer exposes the connecting area, a plurality of cathodes formed on the organic electroluminescent layer, wherein at least a portion of cathodes exposes the connecting area, a protective layer having a plurality of first openings formed on the transparent substrate, wherein the first openings expose the connecting area and a portion of the cathodes, and a plurality of polysolder interconnections formed on exposed connecting area and the portion of the cathode for forming a polysolder interconnection array, the process comprising:

providing a printed circuit board having a plurality of bonding pads;

forming a plurality of bumps on the bonding pads;

forming a filler on the printed circuit board;

disposing at least one organic electroluminescent panel on the printed circuit board;

performing a reflow process for electrically connecting the polysolder interconnections with the bumps; and

crosslinking the filler.

2. The process of packaging an organic electroluminescent panel of claim 1, wherein the bumps are formed on the bonding pads via a wiring bonder.

3. The process of packaging an organic electroluminescent panel of claim 1, wherein the polysolder interconnections are comprised of silver paste.

4. A method of forming an organic electroluminescent panel, comprising:

providing a transparent substrate;

forming a plurality of anodes on the transparent substrate, wherein each of the anodes has a driving area and at least one connecting area laterally connected to the driving area;

forming a patterned organic electroluminescent layer on the transparent substrate or on the anodes, wherein the patterned organic electroluminescent layer exposes the connecting area;

forming a plurality of cathodes on the organic electroluminescent layer, wherein at least a portion of cathodes exposes the connecting area;

forming a protective layer on the transparent substrate, wherein the protective layer comprises a plurality of first openings and wherein the first openings expose the connecting area and a portion of the cathodes; and

forming a plurality of polysolder interconnections on exposed connecting area and the portion of the cathode for forming a polysolder interconnection array.

5. The method of forming an organic electroluminescent panel of claim 4, wherein the anodes are comprised of indium tin oxide.

6. The method of forming an organic electroluminescent panel of claim 4, wherein the cathodes are comprised of metal.

7. The method of forming an organic electroluminescent panel of claim 4, wherein the polysolder interconnections are comprised of silver paste.

8. The method of forming an organic electroluminescent panel of claim 4, wherein the method of forming the polysolder interconnections comprises a screen printing process or a dispensing process.

9. The method of forming an organic electroluminescent panel of claim 4, wherein the method of forming the patterned organic electroluminescent layer comprises:

forming an organic electroluminescent layer; and

defining the organic electroluminescent layer for forming a plurality of second openings thereon, wherein the second openings expose the connecting area.

10. The method of forming an organic electroluminescent panel of claim 4, wherein the method of forming the patterned organic electroluminescent layer comprises:

forming an organic electroluminescent layer; and

defining the organic electroluminescent layer for forming a plurality of strips thereof and exposing the connecting area.

11. The method of forming an organic electroluminescent panel of claim 4, further comprising forming a hole injection layer between the anodes and the organic electroluminescent layer after forming the anodes and before forming the organic electroluminescent layer.

12. The method of forming an organic electroluminescent panel of claim 11, wherein further comprising forming a hole transporting layer between the hole injection layer and the organic electroluminescent layer after forming the hole injection layer and before forming the organic electroluminescent layer.

13. The method of forming an organic electroluminescent panel of claim 4, further comprising forming an electron injection layer between the cathodes and the organic electroluminescent layer after forming the organic electroluminescent layer and before forming the cathodes.

14. The method of forming an organic electroluminescent panel of claim 13, wherein further comprising forming an electron transporting layer between the electron injection layer and the organic electroluminescent layer after forming the organic electroluminescent layer and before forming the electron injection layer.

15. The method of forming an organic electroluminescent panel of claim 4, wherein the method of forming the protective layer comprises:

forming an organic moisture resistant layer; and

forming an inorganic moisture resistant layer on the organic moisture resistant layer.